

ABSTRACT

In known technologies described in Patent Documents 2 and 3, a line conductor or a via conductor has a connecting land. Therefore, when a ceramic substrate is produced, an occurrence of poor connection resulting from a discrepancy between positions of the via conductor and the line conductor, individual working errors, and the like can be prevented by the connecting land. For example, as shown in Fig. 8(a), since a connecting land 3 juts from a via conductor 2 toward an adjacent via conductor 2 side, a reduction of pitch between the via conductors 2 and 2 is hindered by the amount of jut.

An internal conductor connection structure 10 of the present invention is a connection structure connecting first and second via conductors 12 and 13 adjacent to each other in a ceramic multilayer substrate 11 to a first line conductor 15 disposed in the ceramic multilayer substrate 11, wherein the first via conductor 12 includes a first continuous via conductor 17 disposed extending in a direction farther from the second via conductor 13, and the first via conductor 12 is connected to the first line conductor 15 through the first continuous via conductor 17.